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City: Osaka			
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Additional name/s & address/es attached? ☐ Yes ☒ No			
ution date of the application is:  September 12, 2002			
B. Patent No(s).  (1)  (2)  (3)  s attached  Yes  No			
6. Total number of applications & patents involved: 1			
7. Total fee (37 CFR 3.41) \$ 40.00			
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**REEL: 013468 FRAME: 0044** 

			Case No.:	
	ASSIGNMENT OF U.S. PATENT APPLICATION			
	Masataka NISHIKAWA of Nara-shi, Nara, Japan			
(Inventors)		14.		
,				
<b>(A </b>	considerations paid hereby does assign	d to each of the undersigned n, transfer and set over to	ar (\$1.00) and other good and valuable I, the undersigned agree(s) to assign, and	
(Assignee) (Address)	SHARP KABUSHI	e-cho. Abeno-ku. Os	a corporation of <u>Japan</u> aka-shi, Osaka, Japan	
(Title)	(hereinafter designated as the Assignee) the undersigned's entire right, title and interest for the United States, its territories, dependencies and possessions in the invention, and all applications for patent and any Letters Patent which may be granted therefore, known as SEMICONDUCTOR MODULE AND PRODUCTION METHOD THEREFOR AND MODULE FOR IC CARDS AND THE LIKE			
	patent in the United	d States of America or, if no	on even date herewith an application for ton even date, then has executed on S. application Serial No, on	
		 icknowledges an obligation on the invention was made.	of assignment of this invention to said	
application or and also to ex deem necess claims or pro- agreements.	r any interference wheele who are asset as a common and a	nich may be declared and ar ignments in connection with d further to perform any act ational Convention for Protec	documents necessary in connection with the ry continuing or divisional applications thereof such applications as the Assignee may which may be necessary in connection with ction of Industrial Property or similar	
The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.				
The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patent of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.				
The undersigned hereby grant(s) the firm of NIXON & VANDERHYE P.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document. It is understood and agreed that ASSIGNEE'S attorneys Nixon & Vanderhye P.C. have represented only ASSIGNEE and will continue to represent only ASSIGNEE with respect to this invention.  In witness whereof, executed by the undersigned on the date(s) opposite the undersigned				
signature(s).	mess whereor, exce	ated by the undersigned on		
Date Sept	ember 12, 2002	Signature of inventor	Masataka Prishikawa	
Date		Signature of inventor		
Date		Signature of inventor		
Date		Signature of inventor		
Date		Signature of inventor		
Witnessed by	/:		Date	
Witnessed by	<i>/</i> :		Date	

**RECORDED: 11/07/2002** 

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PATENT REEL: 013468 FRAME: 0045